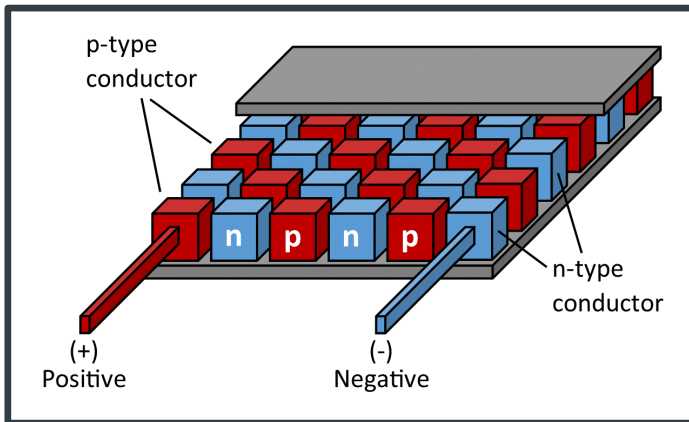


Low-pressure chemical vapour deposition synthesis of metal-chalcogenide materials for thermoelectric micro-generator applications

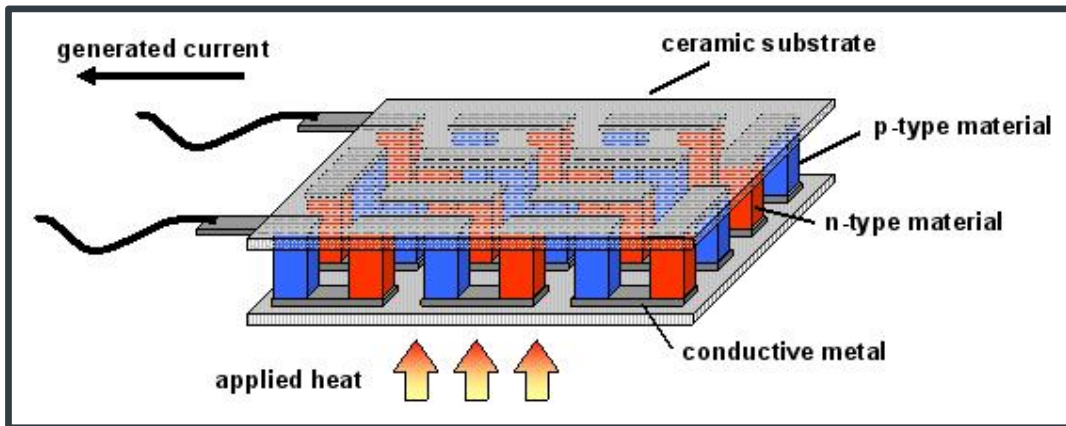
Dr Stephen Richards

14th February 2018

Context and outline

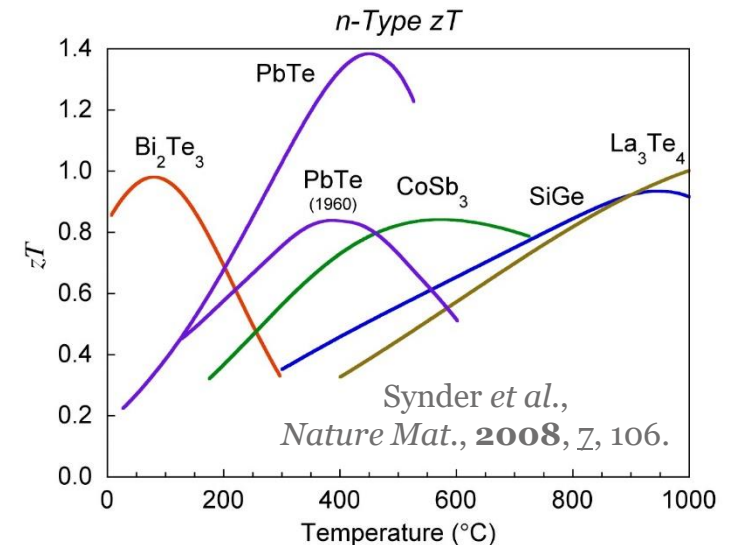
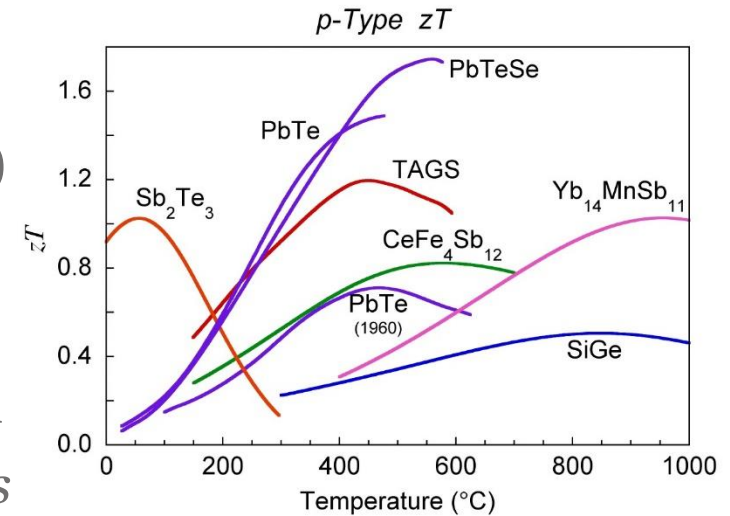


- Why Chemical Vapour Deposition (CVD)
- Binary film deposition/characterisation
- Area selective deposition study trials
- Selective CVD in test device construction
- *Ternary materials - tuning of properties*

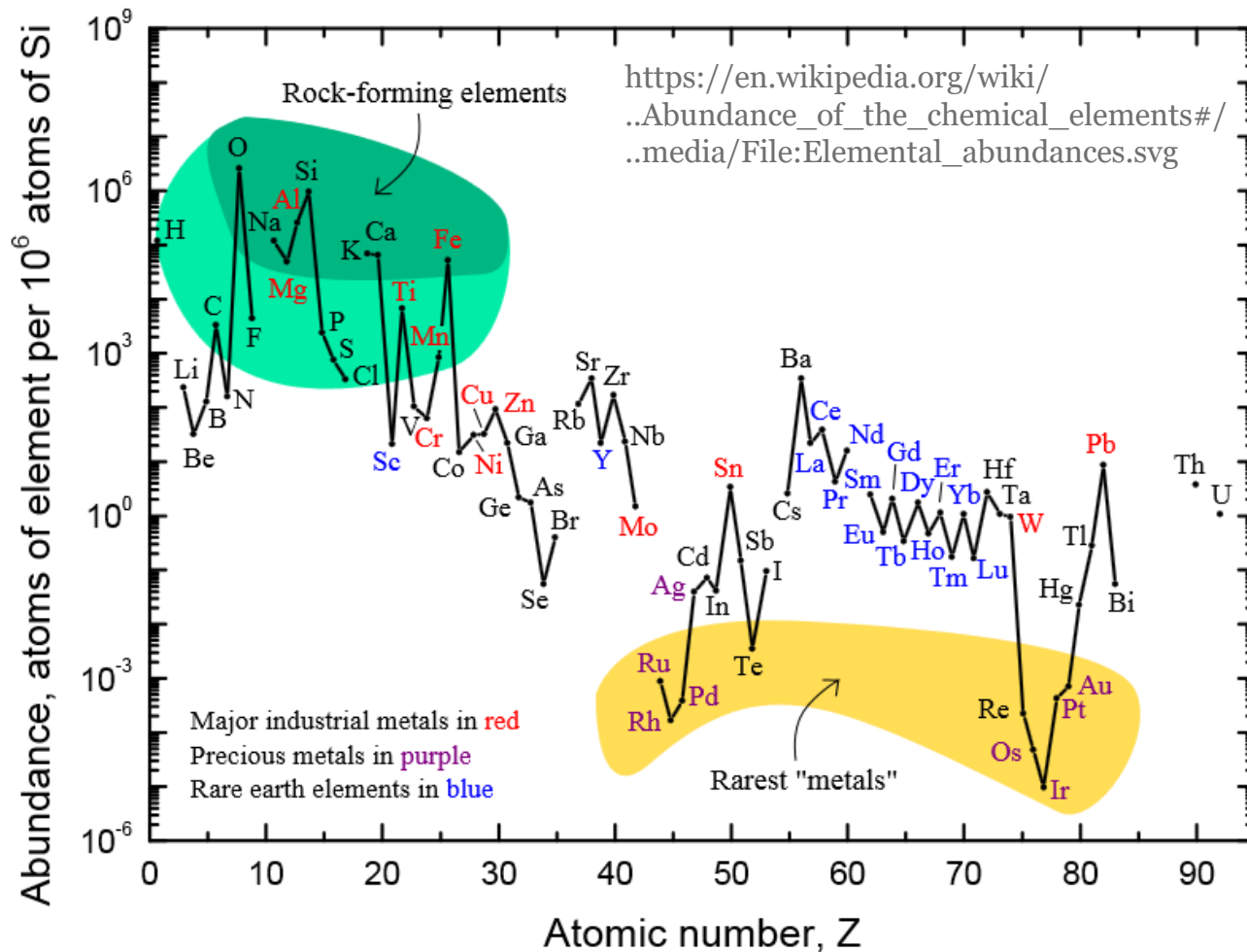


Dimensionless figure of merit

$$ZT = \frac{\alpha_{eff}^2 \sigma_{eff}}{k_{eff}} T$$

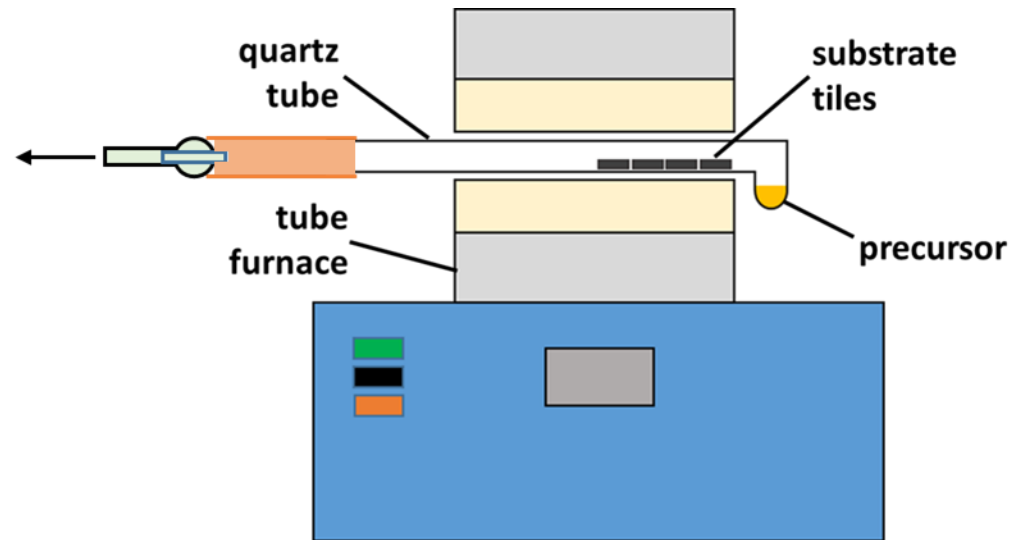


Why Chemical Vapour Deposition?



- Low abundance of Te makes *bulk* thermoelectric generator devices unaffordable – thin film devices
- Advantages of *thin film* material deposition by CVD include:
 - Low cost (ease of operation)
 - Scalability (simple engineering)
 - Good quality conformal films
 - Substrate selectivity

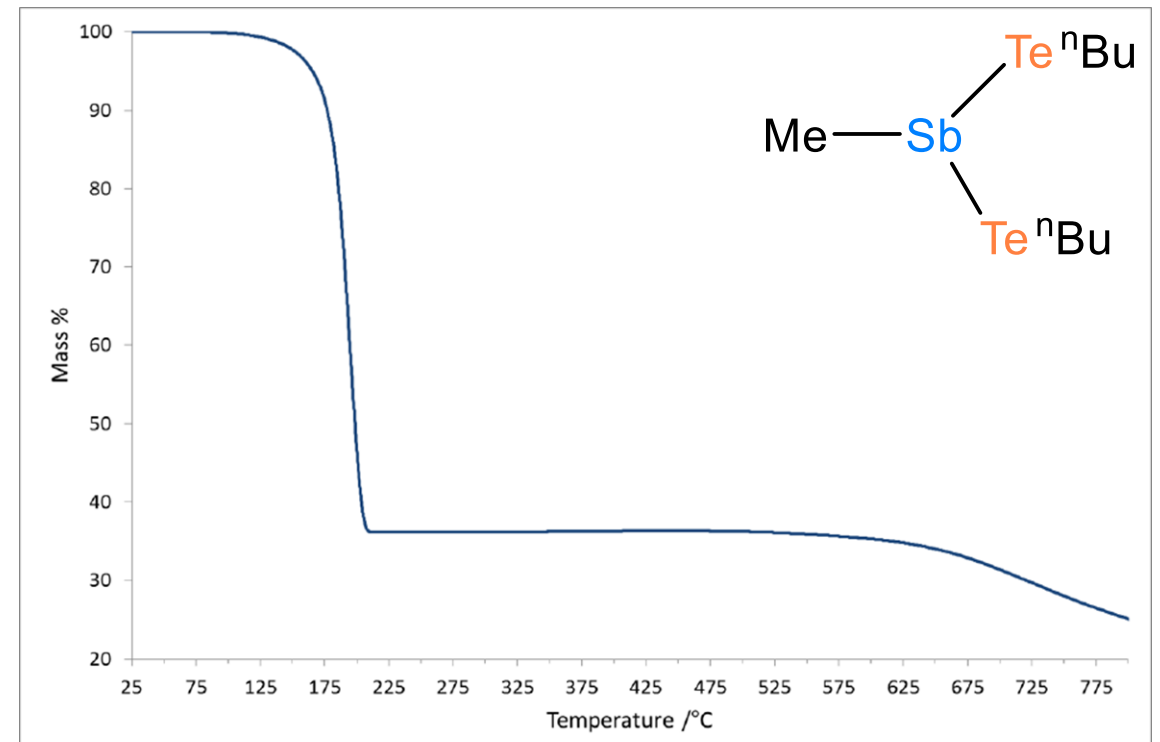
Thin film materials deposition



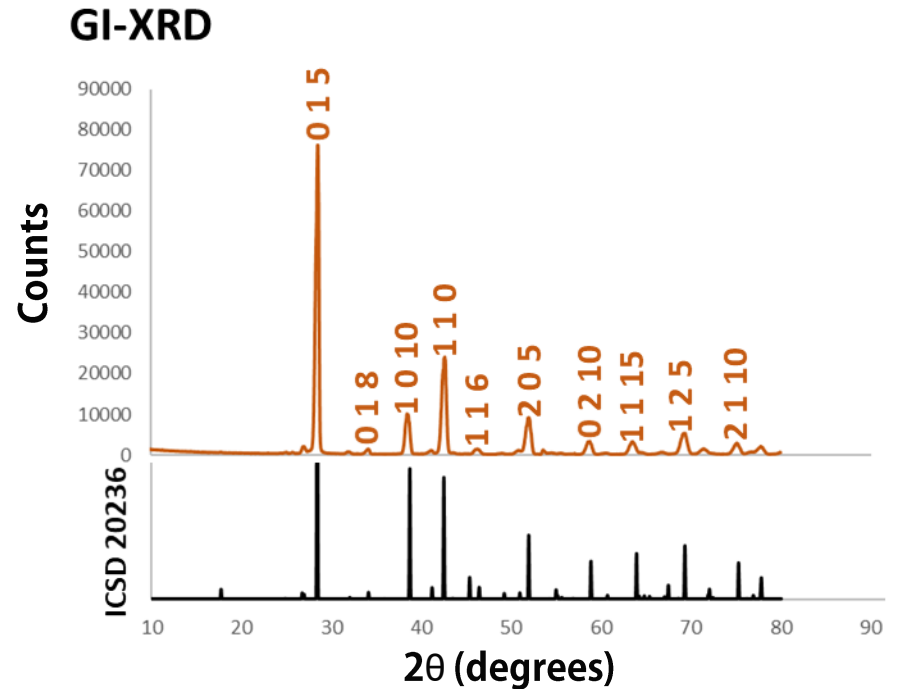
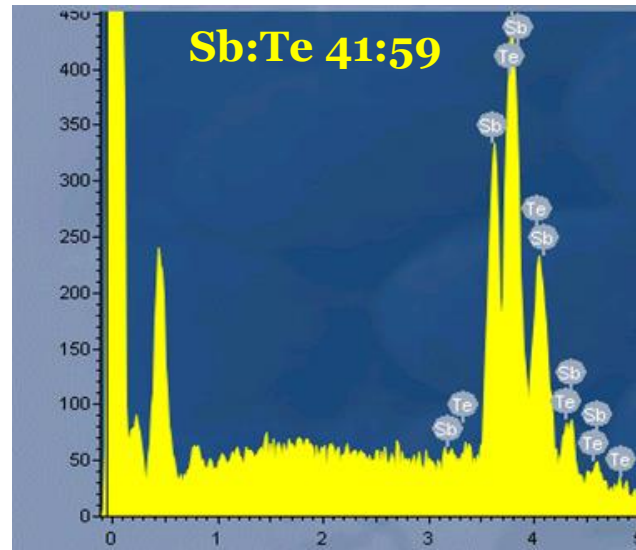
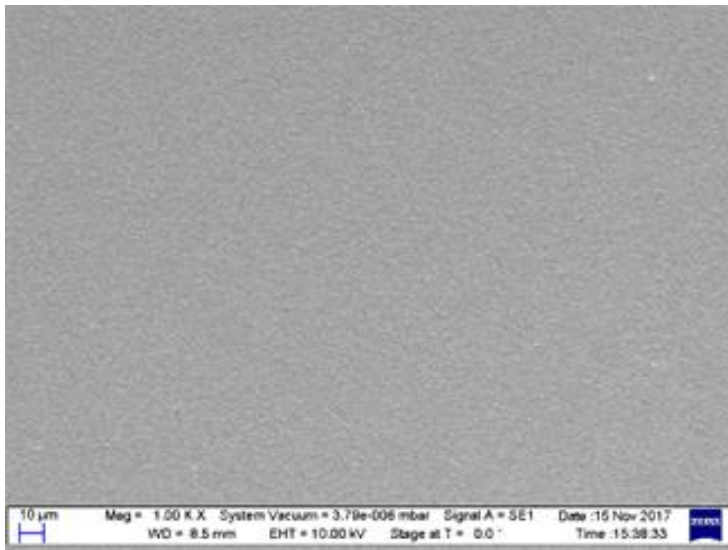
- Typical LPCVD process condition parameters:
 - Pressure: <0.1 Torr
 - Furnace set point (max temperature): $450\text{ }^{\circ}\text{C}$ to $550\text{ }^{\circ}\text{C}$ (dependent on material deposited)
 - Substrate position determines deposition temperature/precursor concentration

Single source Sb_2Te_3 precursor

- Organometallic tellurolate precursor
 - Strong bonds between constituents
 - Relatively low molecular weight
 - High purity: NMR, elemental (CHN)
 - Close to desired film stoichiometry
- TGA suggests suitability of $[(\text{Me})\text{Sb}(\text{Te}^n\text{Bu})_2]$
 - High volatility (Sb_2Te_3 c.f. 49% precursor)
 - Low decomposition temperature
- Precursor lifetime: >6 months (freezer)



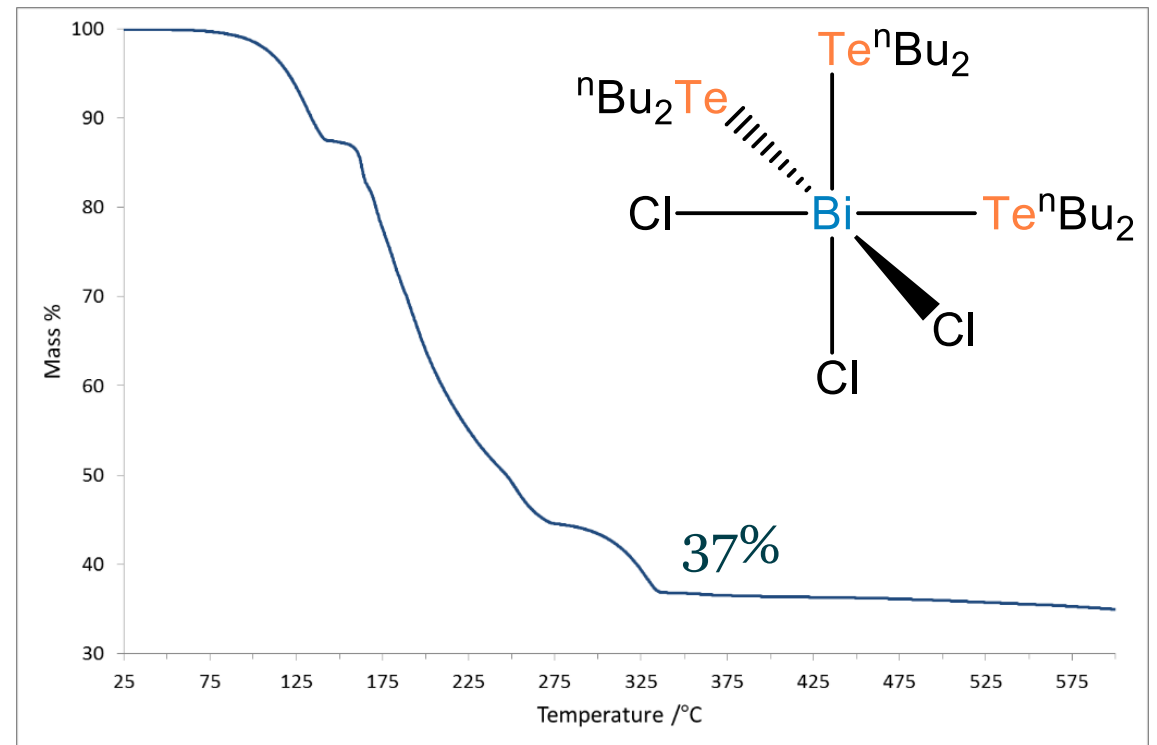
Sb₂Te₃ thin film deposition: SiO₂



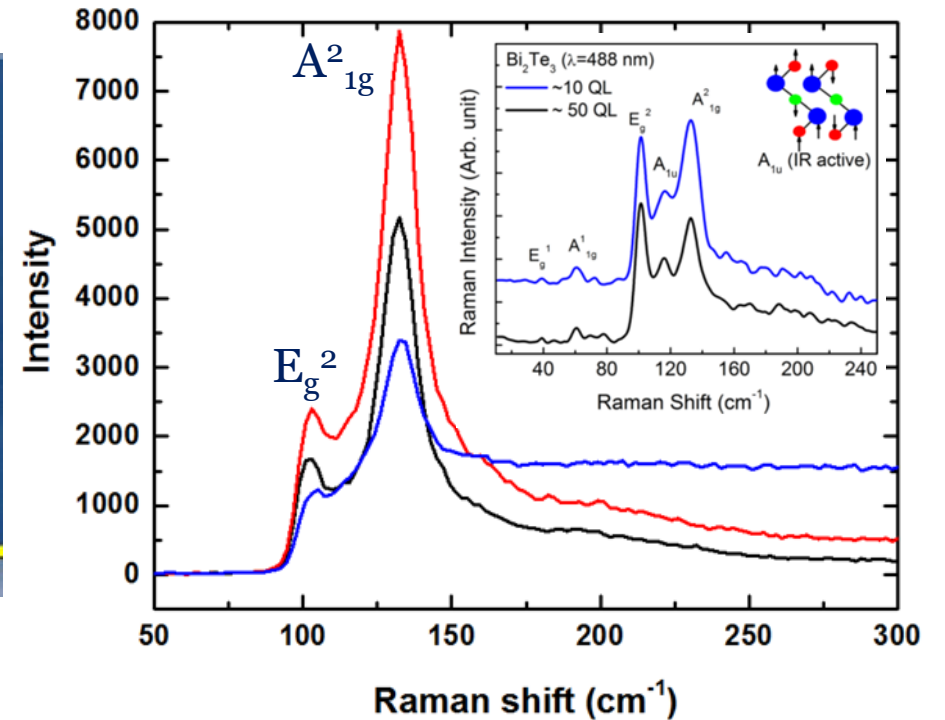
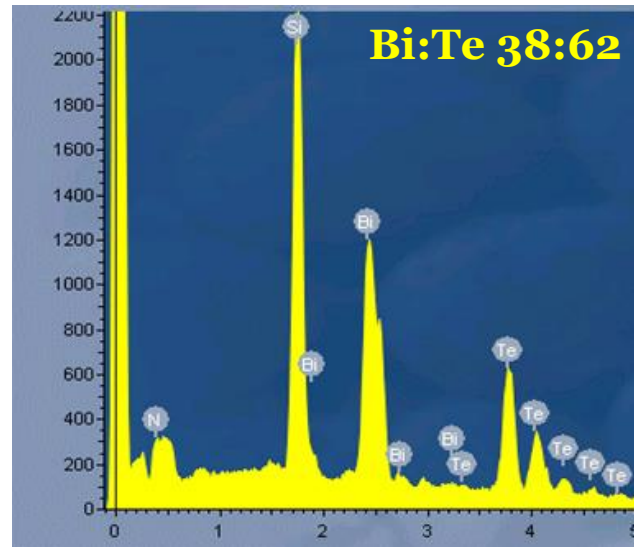
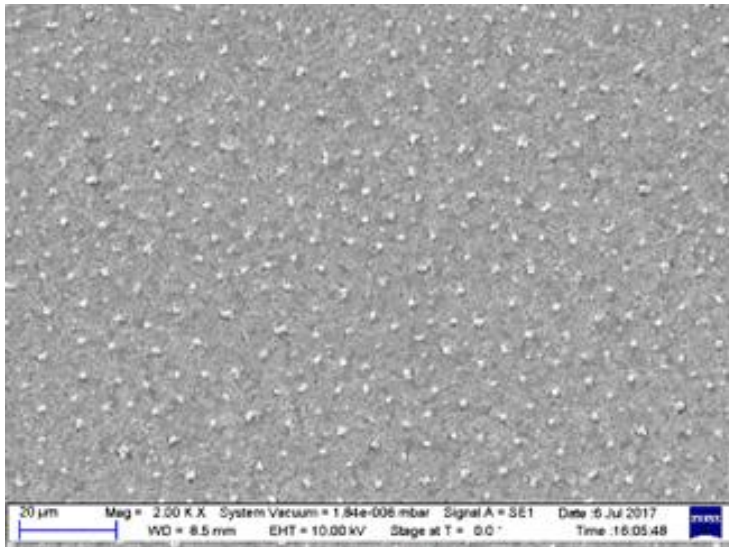
- p-type semiconductor
- Continuous thin film with no detected impurities
- Polycrystalline (tellurantimony) Sb₂Te₃ phase
 - Refined unit cell parameters: $a, b = 4.239(4)$, $c = 30.27(8)$ Å; $\alpha, \beta = 90^\circ$, $\gamma = 120^\circ$

Single source Bi_2Te_3 precursor

- Direct bonds between constituent elements
 - Pure: NMR, CHN, IR [$\nu(\text{Bi-Cl})$: 247 cm^{-1}]
 - Precise control over film composition
 - Reproducibility with simple apparatus
- TGA suggests suitability of $[(n\text{Bu}_2\text{Te})_3\text{BiCl}_3]$
 - Residue approximating Bi_2Te_3 (c.f. 38%)
 - Low temperature decomposition
 - Clean decomposition (no contaminants)
- Precursor lifetime: >10 months (freezer)



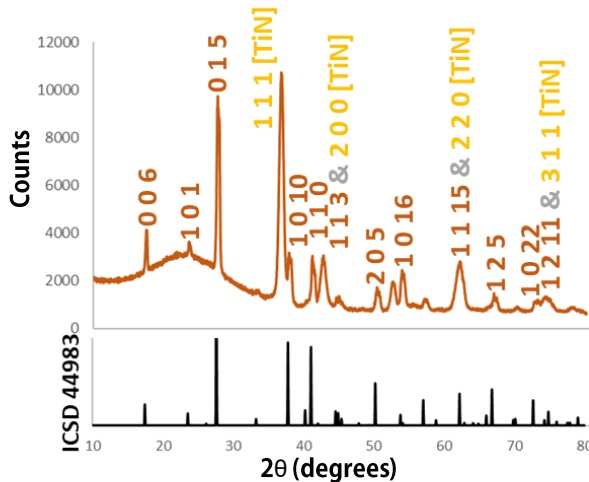
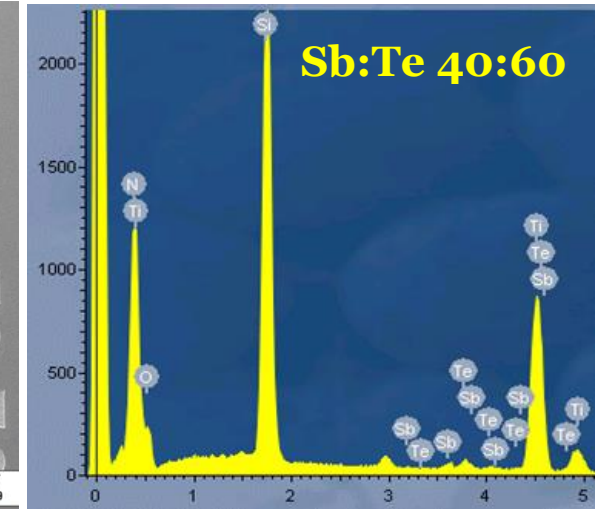
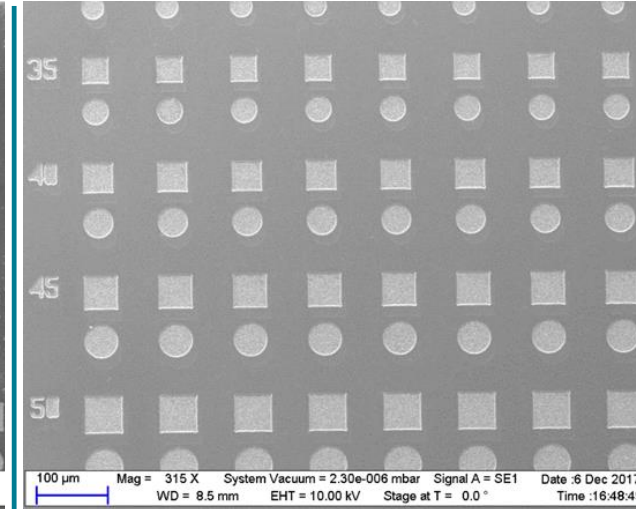
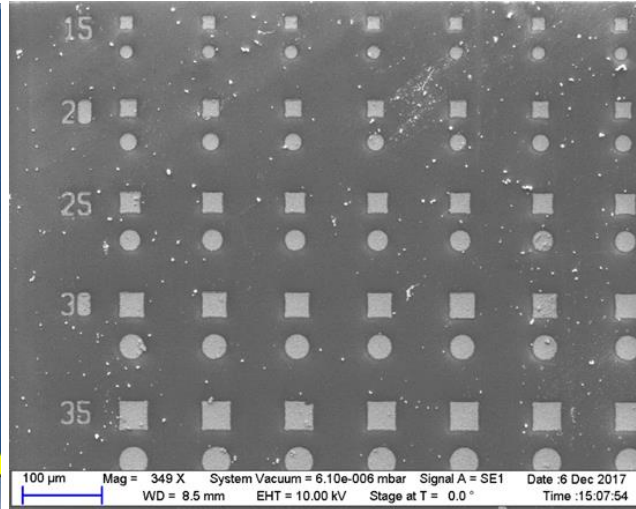
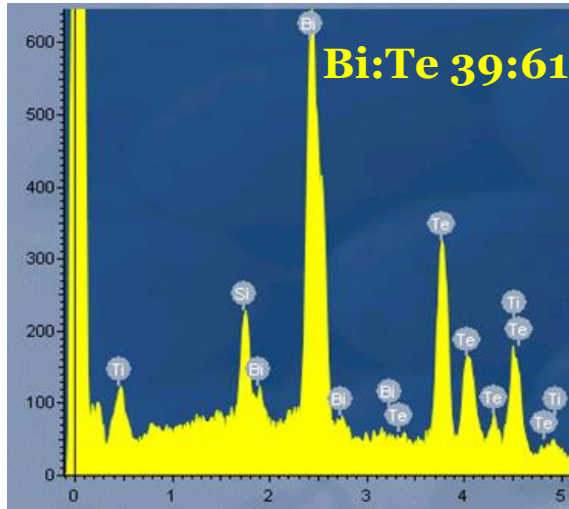
Bi₂Te₃ thin film deposition: Si_xN_y



- n-type semiconductor
- Continuous thin film with no detected impurities
- Polycrystalline (tellurobismuthite, syn) Bi₂Te₃ phase
 - Refined unit cell parameters: $a, b = 4.3839(17)$, $c = 30.52(2)$ Å; $\alpha, \beta = 90^\circ$, $\gamma = 120^\circ$

Balandin *et al.*, *J. Appl. Phys.*, 2012, **111**, 054305.

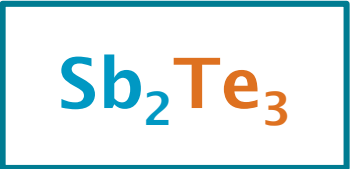
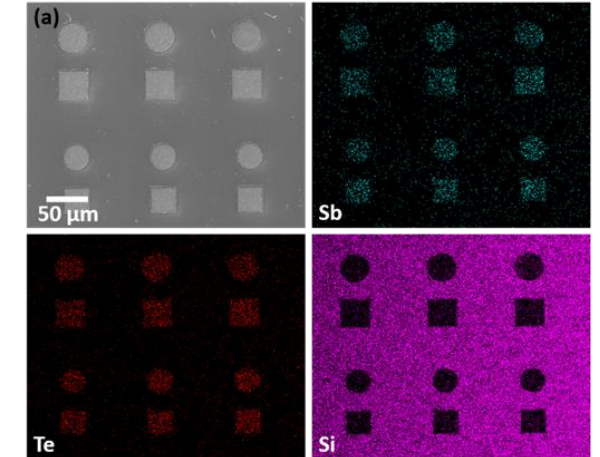
Selective deposition: Ti_xN_y/SiO_2



Above: Selective deposition
Top left: EDX spectrum
Left: Grazing incidence XRD

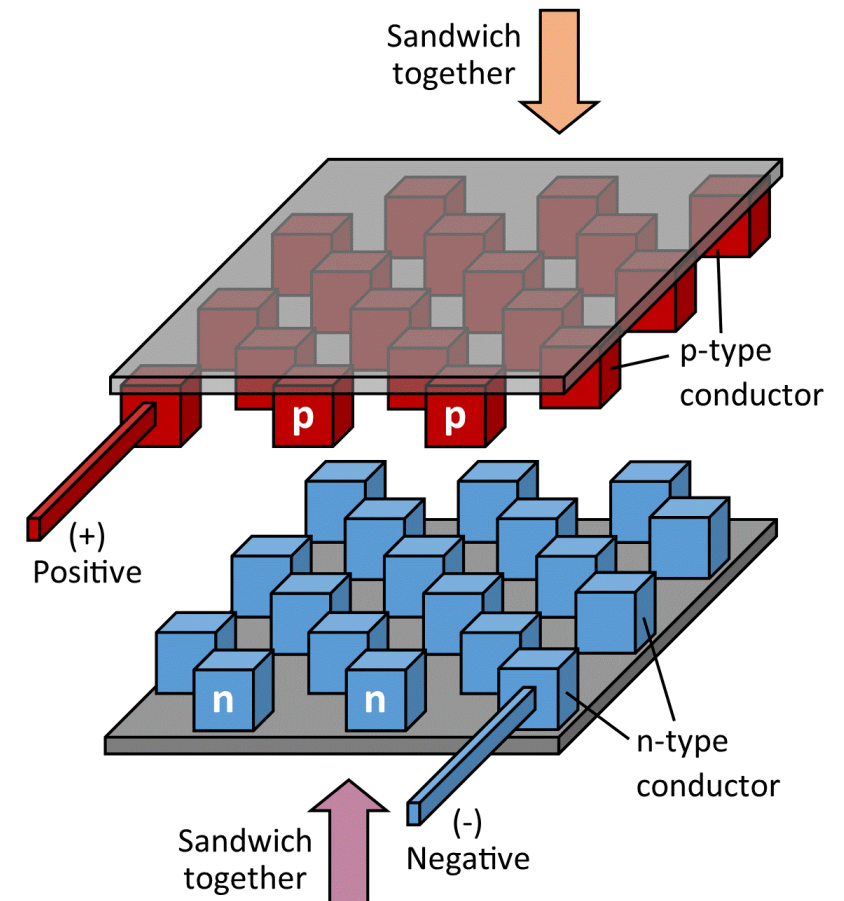


Above: Selective deposition
Top right: EDX spectrum
Right: EDX element map



Micro-generator fabrication

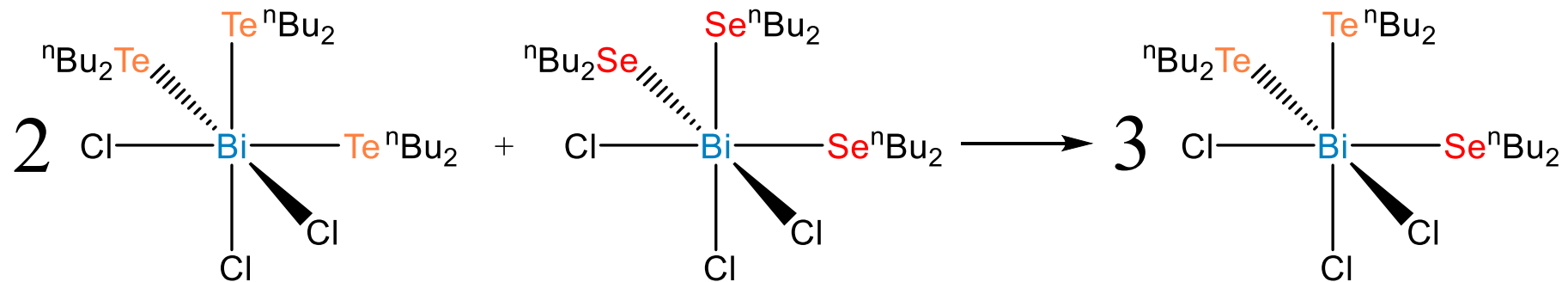
- Conventional fabrication is laborious, complicated and costly
 - Deposition (separate lithographic processing steps for both n- & p-type materials)
 - Wasteful additional patterning (both n- & p-type materials)
 - Soldering and bonding
- Impacts on thermoelectric micro-generator performance
 - Thermoelectric material damage (etching/contacting)
 - Parasitic contact resistance due to soldering
 - Problematic limited thermoelectric performance often the case with contacted sputtered materials
- *Selective deposition* confined to conductive domains within device-patterned substrates a simpler more elegant approach



Ternary bismuth chalcogenides

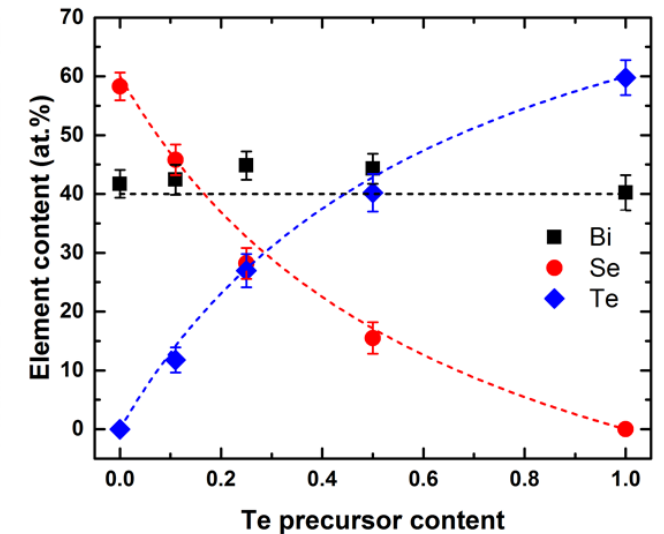
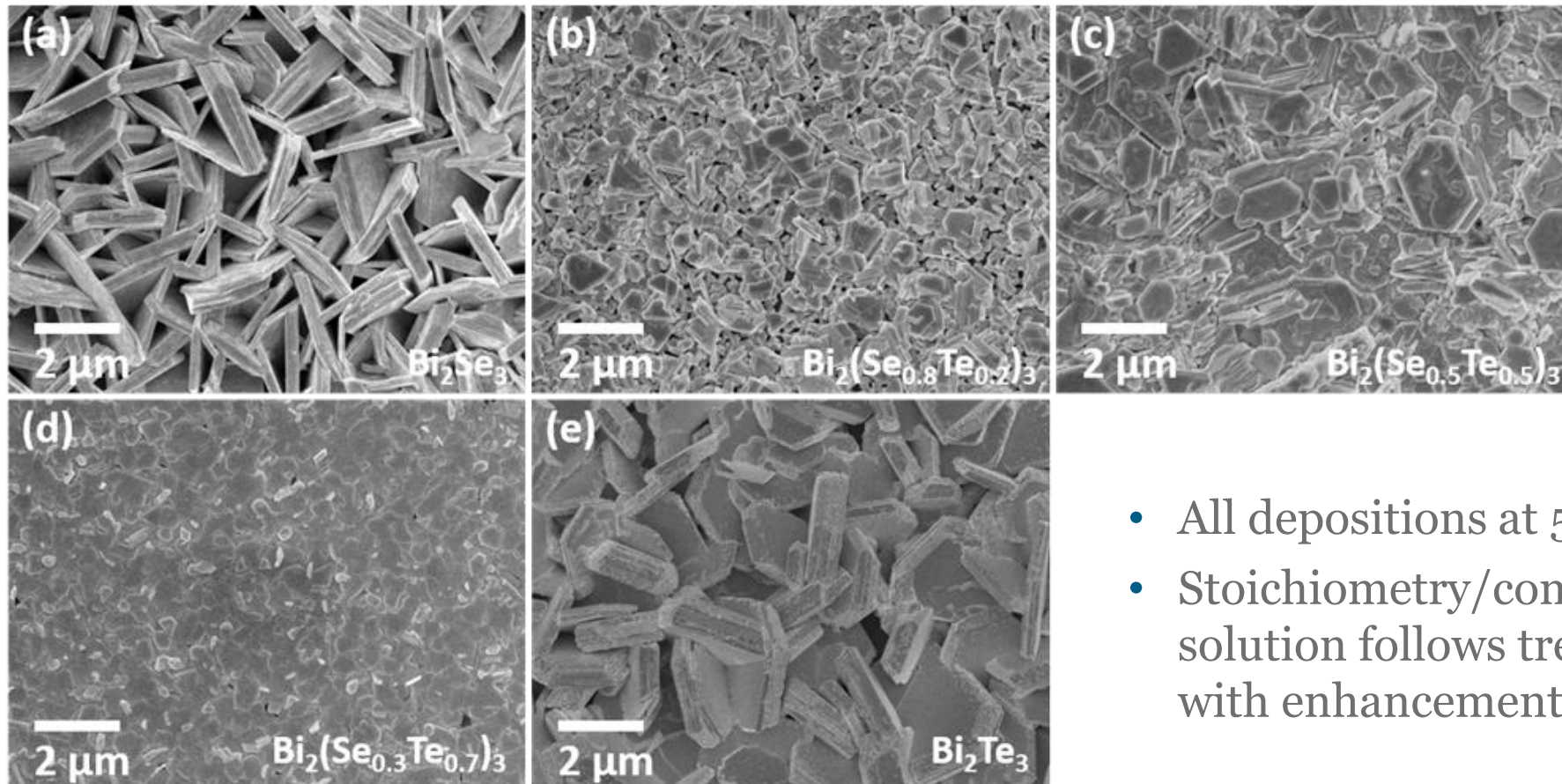


- Tuning of thermoelectric material properties (esp. relative to metal interconnects)
- Tight control over stoichiometry (compatible reagents, or preferably single reagent)



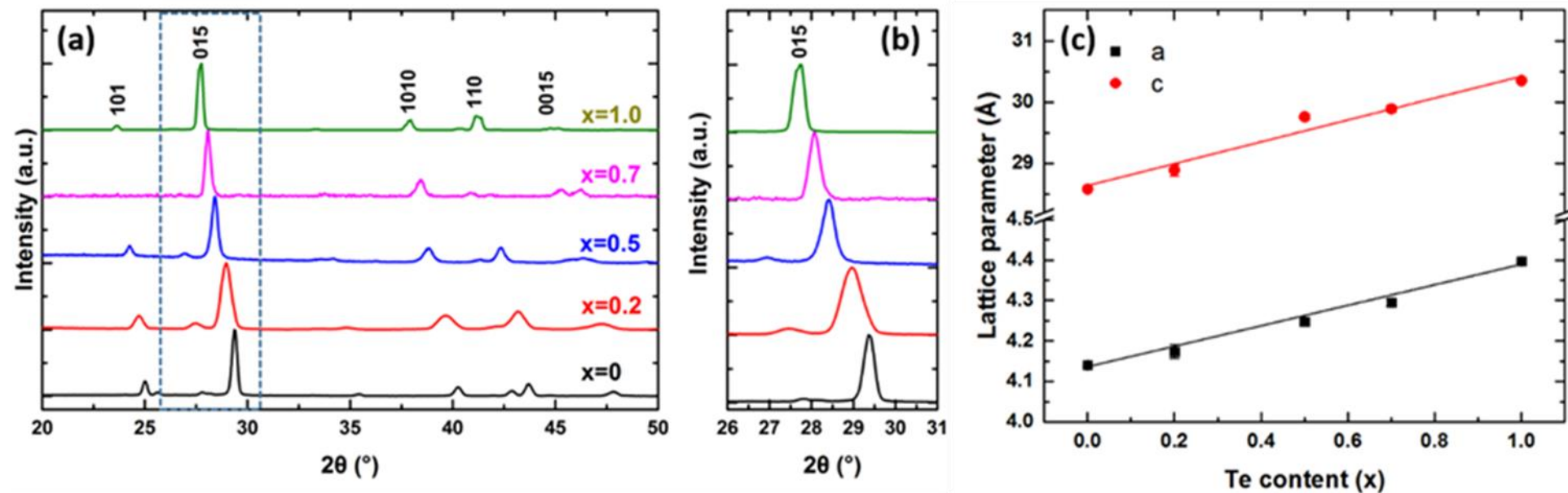
- Take advantage of lability of $[(^n\text{Bu}_2\text{E})_3\text{MCl}_3]$ systems – where E = Te, Se; M = Bi, Sb
 - Mixing $[(^n\text{Bu}_2\text{Te})_3\text{BiCl}_3]$ and $[(^n\text{Bu}_2\text{Se})_3\text{BiCl}_3]$ causes ligand scrambling – statistical mixture

$\text{Bi}_2(\text{Se}_{1-x}\text{Te}_x)_3$ thin film deposition



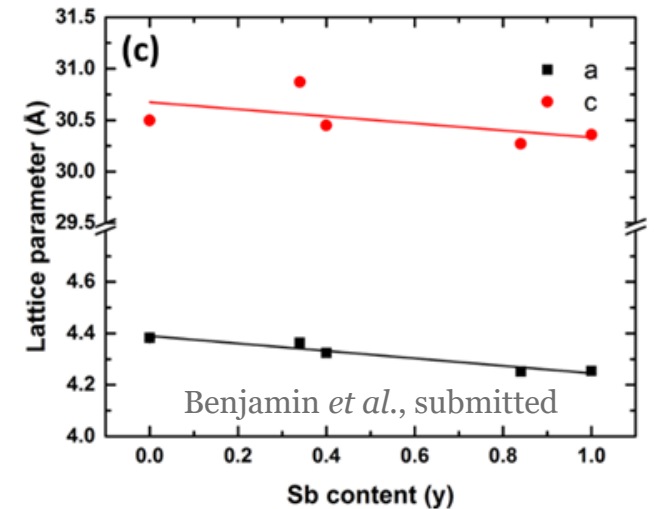
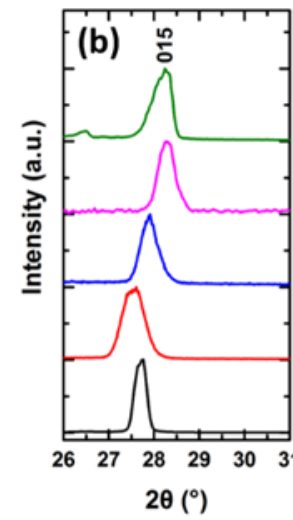
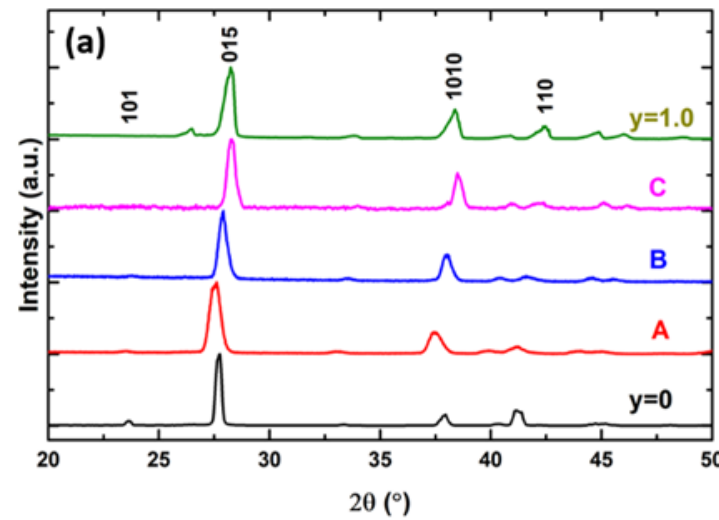
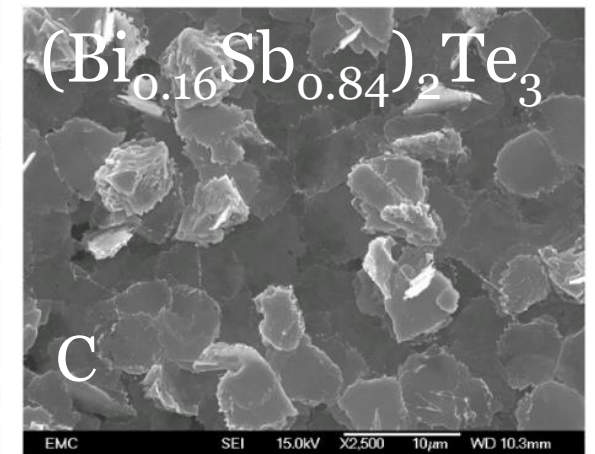
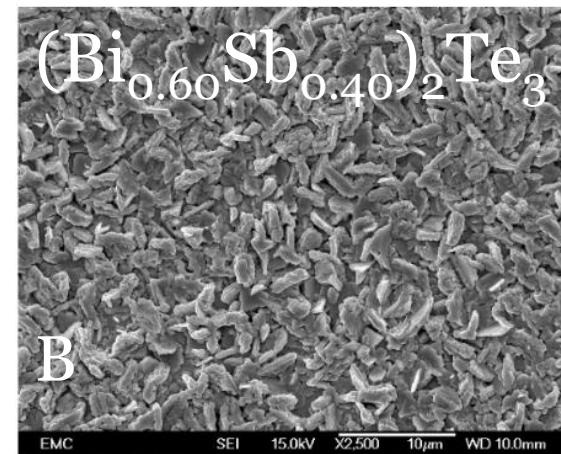
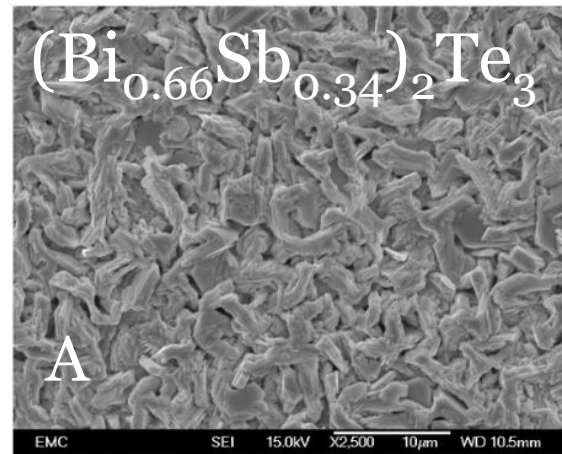
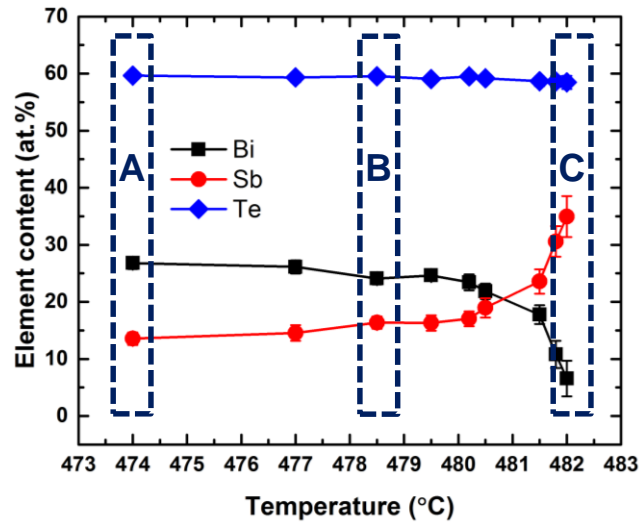
- All depositions at 550 °C
- Stoichiometry/composition (by EDX) of solid solution follows trend precursor formulation with enhancement in Te

Bi₂(Se_{1-x}Te_x)₃ thin film XRD



- Vegard's Law behaviour *vs* EDX analysed compositions for solid solutions
- Some broadening of reflections in solid solutions c.f. binary material phases

$(\text{Bi}_{1-y}\text{Sb}_y)_2\text{Te}_3$ thin film deposition



- Composition *vs* long axis of sample (function of deposition temperature)
- Increase in Sb and decrease in Te with increasing temperature

Conclusions and future work

- Good degree of control using single source precursors – high quality polycrystalline films
 - [$(\text{nBu}_2\text{Te})_x(\text{nBu}_2\text{Se})_{1-x}\text{BiCl}_3$] convenient single source precursors to $\text{Bi}_2(\text{Te,Se})_3$ ternaries
- Substrate selectivity is a major advantage of LPCVD using our precursors for micro-TEGs
 - Materials efficiency to minimise wastage of expensive tellurium (Te)
 - Simpler device construction with fewer steps – anticipated better performance
- Optimisation of ternary phase deposition is ongoing to allow measurements to be undertaken
 - Efficiency requires tuning thermoelectric device element “legs” relative to interconnects
 - Working towards evaluating selective deposition of ternary materials

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